

ABSTRACT

A method for manufacturing a semiconductor device includes a resin sealing step for sealing a semiconductor chip (6) with a resin material (9) in a state where the semiconductor chip (6) is bonded on a lead frame (1) in which a depressed portion (5) is formed, a laser light irradiation step for irradiating the depressed portion (5) with laser light to remove the resin material (9) in the depressed portion (5) by the laser light so that a part (9c) of the resin material (9) remains in the depressed portion (5), and a cutting step for cutting a bottom face (4v) of the depressed portion (5) in the lead frame (1) together with the part (9c) of the resin material (9) in the depressed portion (5).